



2008 IEEE International Ultrasonics Symposium

(Including Short Courses & Tutorials)



November 2-5, 2008

Beijing International Convention Center, Beijing, China

Sponsored by the IEEE Ultrasonics, Ferroelectrics, & Frequency Control Society
In Cooperation with the Acoustical Society of China and the Institute of Acoustics, Chinese Academy of Sciences

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The Great Wall

First Call for Papers

Abstract deadline: **May 4, 2008**

Abstract submission and conference website:

http://ewh.ieee.org/conf/ius_2008/

The annual IEEE International Ultrasonics Symposium (IUS) will be held at the Beijing International Convention Center (BICC), Beijing, China, from November 2-5, 2008. This will be the first time that the IUS will take place in China. Beijing is the capital of China and has a long history and a great culture. It will also host the 2008 Summer Olympics and Paralympics, which will be held in August and September, 2008. After the Olympics, Beijing will have decorated city streets, improved infrastructure, cleaner environment, and greatly increased hotel capacity. The 2008 IUS will take advantage of this historic opportunity to offer conference attendees and their guests not only an excellent technical program, but also an opportunity to explore the rich culture and visit tourist attractions of Beijing and the rest of China. The BICC is located within the Olympic Complex.

Papers are solicited for this conference describing original work in the field of ultrasonics. Poster and oral presentation formats will be used at the symposium. Prospective authors should note that poster sessions provide an alternative format which allows for greater flexibility and expanded audience interaction.

The deadline for submission of abstracts is **May 4, 2008**. The abstracts should be submitted in electronic form according to the specific information posted on the conference web page. Additional conference information can be found at the Symposium web site: http://ewh.ieee.org/conf/ius_2008/. Each abstract will receive careful review and evaluation by the Symposium Technical Program Committee. Evaluation criteria will include originality of the work, contribution to the state-of-the-art, and overall interest to the ultrasonics community. Authors are required to concisely divide their abstract into three sections: **I. Motivation/Background; II. Statement of the Contribution/Methods; III. Result/Discussion**. Papers are solicited from the following **subject classifications**:

Group 1: Medical Ultrasonics

MBB Medical Beamforming and Beam Steering
MBE Biological Effects & Dosimetry
MBF Blood Flow Measurement
MCA Contrast Agents
MEL Elastography
MIM Medical Imaging
MSP Medical Signal Processing
MTC Medical Tissue Characterization
MTH Therapeutics, Hyperthermia, Ultrasound in Surgery

Group 2: Sensors, NDE & Industrial Applications

NAM Acoustic Microscopy
NAI Acoustic Imaging
NAS Acoustic Sensors
NDE General NDE Methods
NFM Flow Measurement
NMC Material & Defect Characterization
NPM Wave Propagation
NSP Signal Processing
NTD Transducers: NDE and Industrial

Group 3: Physical Acoustics

PBW Bulk Wave Effects & Devices
PGP General Physical Acoustics
PMI Magnetic/Electromagnetic Interactions
POI Optical Interactions
PUM Ultrasonic Motors & Actuators
PTF Thin Films

Group 4: Microacoustics – SAW, FBAR, MEMS

MMP Materials & Propagation
MDM Device Modeling
MDD Device Design
MDA Device Applications

Group 5: Transducers & Transducer Materials

TMC Transducers: Materials Characterization and Fabrication Technology
TPF Transducers: Piezoelectric and Ferroelectric Materials
TMO Transducer Modeling (Analytical & Numerical)
TMT Medical Transducers
TMU Micromachined Ultrasound Transducers

Student Travel Support: Limited funds are available to support **IEEE UFFC student member attendees** at the 2008 symposium. Awards will be given on a competitive basis. Please see the conference website for details.

Student Paper Competition: Students submitting abstracts are invited to participate in a student paper competition. To participate, the student must be the lead author and present his/her paper. Further information will be posted on the conference website.

Visa Application: Please visit the Symposium web site for updated information regarding invitation letters, and apply in advance if you need a visa to travel to China. The information is expected to be available in February 2008.